

REMARKS

Claims 1, 4 to 8 and 11 to 14 are pending in the above-referenced application and are submitted for the Examiner's reconsideration.

Claims 12 and 13 have been corrected to address minor grammatical errors. Approval and entry are respectfully requested.

With respect to paragraph four (4) of the Final Office Action, claim 14 was rejected under 35 U.S.C. § 112 because it is assertedly a duplicate of claim 1.

The rejection is traversed. Claim 14 depends from claim 13, which depends from claim 12, which depends from claim 11. As to claim 11, its equipping, seeding and depositing clauses as recited differ from one another. Accordingly, claim 14 is not duplicative of claim 1. It is therefore respectfully requested that the rejection be withdrawn.

With respect to paragraph five (5), claims 1, 4 to 8 and 11 to 14 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over United States Patent No. 6,406,939 ("Lin") in view of United States Published Patent Application No. 2003/0080392 ("Zuniga-Ortiz"), and United States Patent No. 6,372,539 ("Bayan") and Official Notice.

It is noted that as to the Official Notice, the Office cites as an example, column 8, lines 34 to 40, of the Lin reference to evidence that it is "well known in the art of printed circuit components to fire components to bond them to one another after formation of the components". However, this cited text only refers to melting conventional solder to fill the lower part of via holes, so that the solder 610 adheres to sidewalls of the via holes and input/output terminal pads 602 of an integrated circuit chip 601 to provide electrical and mechanical contacts.

In contrast, claim 1 relates to a method for producing a conductive layered coating on an insulating substrate, the method including equipping, in selected regions, at least one surface of an electrically insulating substrate with a coating of an electrically highly conductive first metal, the coating being structured as conductor paths, cleaning the at least one coated surface, seeding the coating with seeds of a second metal, depositing a layer including an alloy of the second metal onto the coating seeded with the seeds of the second metal, firing the substrate deposited with the layer of the second metal to form the conductive layered coating, and contacting a gold bonding wire to the conductive coating. *Claim 1 provides that the firing is performed at a temperature below the melting point of the first metal, the second metal and the alloy, and claim 1 further provides that the substrate*

includes an LTCC, the first metal includes silver, and the second metal includes palladium. Moreover, “firing” is a term of art that is consistent with the use of ceramics, as provided for by the LTCC substrate of claim 1. The other references do not disclose – and are not asserted to disclose – the feature in which the firing is performed at a temperature below the melting point of the first metal, the second metal and the alloy, as provided for in the context of claim 1.

Accordingly, it is respectfully submitted that Lin, Zuniga-Ortiz, Bayan, and the knowledge the Final Office Action asserts to well known, whether taken alone or combined, do not disclose or suggest a method of producing a conductive coating on an electrically insulating LTCC substrate, in which selected regions of the surface of the substrate are equipped with a first metal which is seeded with a second metal and thereupon deposited with an alloy of the second metal and fired at a temperature below the melting points of the first metal, the second metal and the alloy. Indeed, none of the references cited, or the knowledge asserted to be well known (which is not evidenced by the Lin reference as explained above), even refer to an LTCC substrate and the firing of such a substrate at a temperature below the melting points of metal layers applied thereon.

As explained above, col. 8, lines 34 to 40, of Lin only refers to applying a temperature to melt solder – as is well known, which is wholly different than firing at a temperature below the melting point at a temperature below the melting point of the first metal, the second metal and the alloy, as provided for in the context of claim 1. As shown, Lin actually teaches exactly the opposite, and quite clearly refutes the conclusory assertions of the Final Office Action.

Thus, it is respectfully submitted that Lin, Zuniga-Ortiz, Bayan, and the knowledge the Office Action asserts to be well known, whether taken alone or combined, do not disclose or suggest connecting a gold bond wired to the conductive coating formed by the firing of the LTCC substrate, as provided for in the context of claim 1. Indeed, none of the references cited, or the knowledge asserted to be well known (which is not conceded), contemplate such a configuration.

Accordingly, for at least these reasons, claim 1 is allowable.

Claims 4 to 8 depend from claim 1, and therefore are allowable for at least the same reasons as claim 1 as presented.

Claim 11 includes the firing feature like that of claim 1, and is therefore allowable for essentially the same reasons, as are its dependent claims 12 to 14.

Accordingly, claims 1, 4 to 8 and 11 to 14 are allowable.

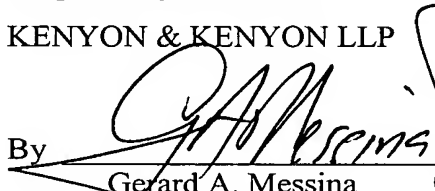
CONCLUSION

In view of all of the above, it is respectfully submitted that all of the presently pending claims are allowable. It is therefore respectfully requested that the objection and rejections be withdrawn. All issues raised by the Examiner having been addressed, an early and favorable action on the merits is respectfully requested.

Respectfully submitted,
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